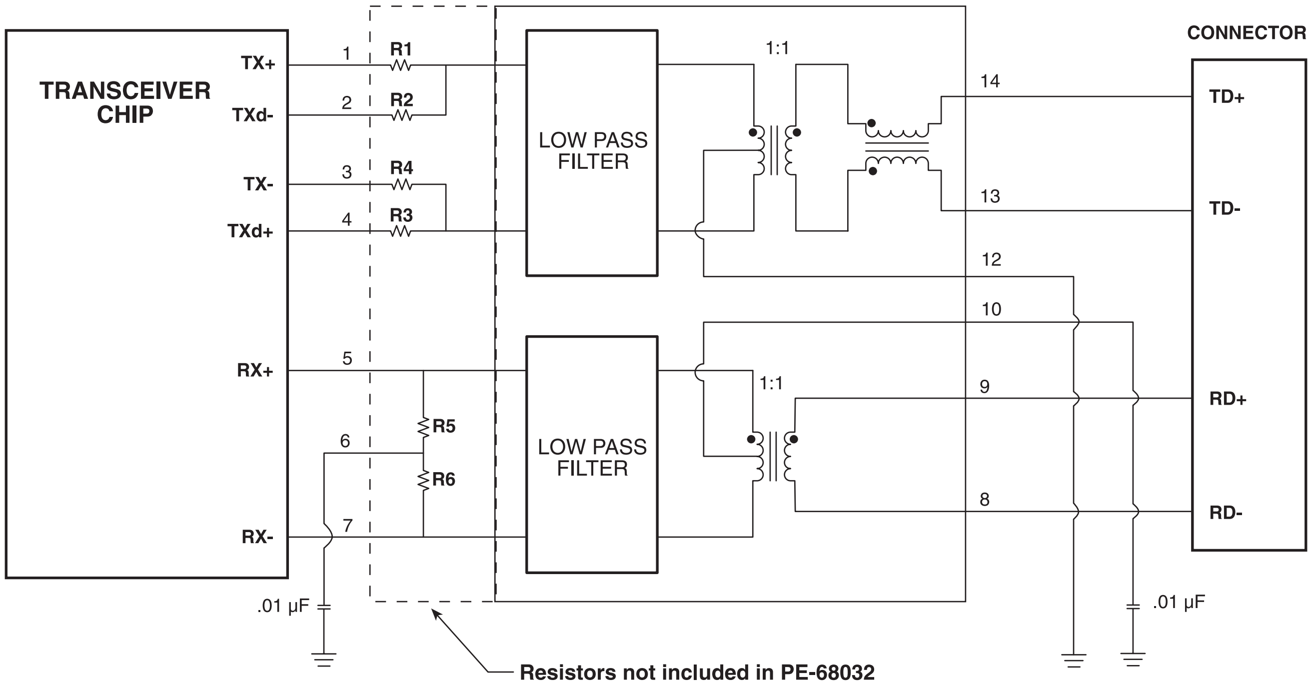
LOW PROFILE SURFACE MOUNT 10BASE-T INTERFACE MODULES

Ideal for Type I or Type II PCMCIA Applications

Application Circuit - A

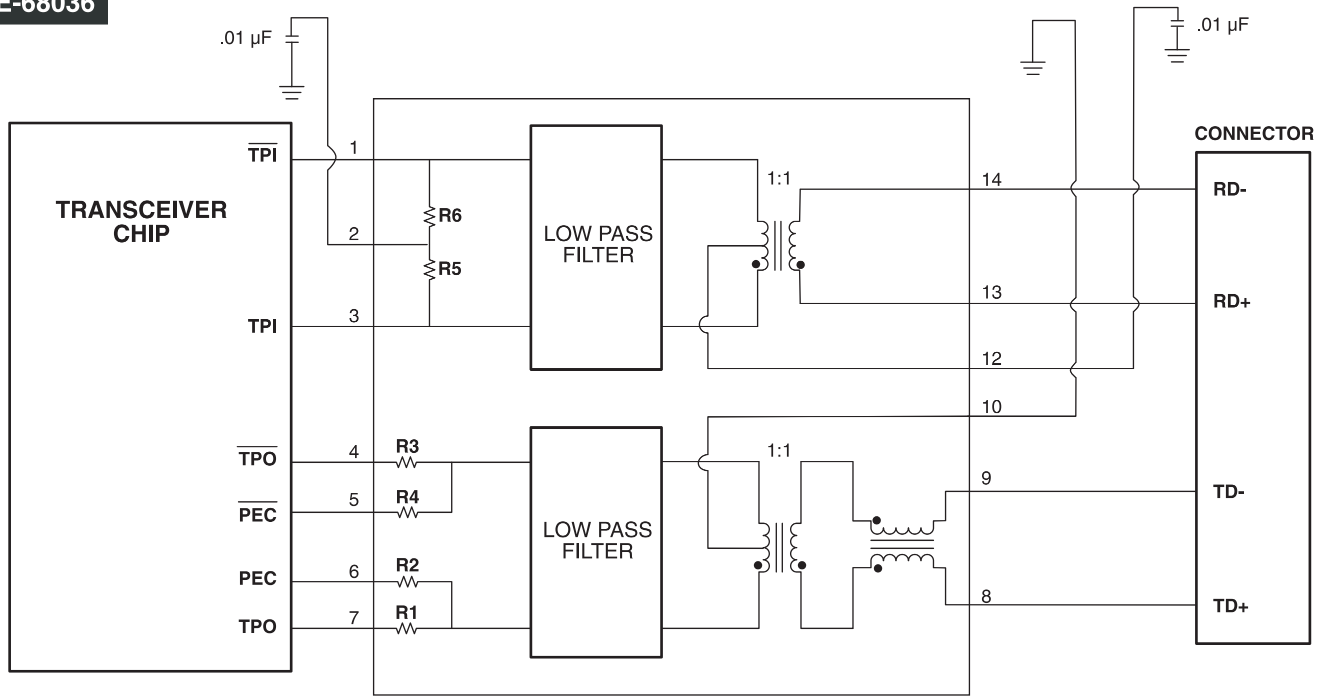
PE-68032 or PE-68035



Resistors not included in PE-68032

Application Circuit - B

PE-68036

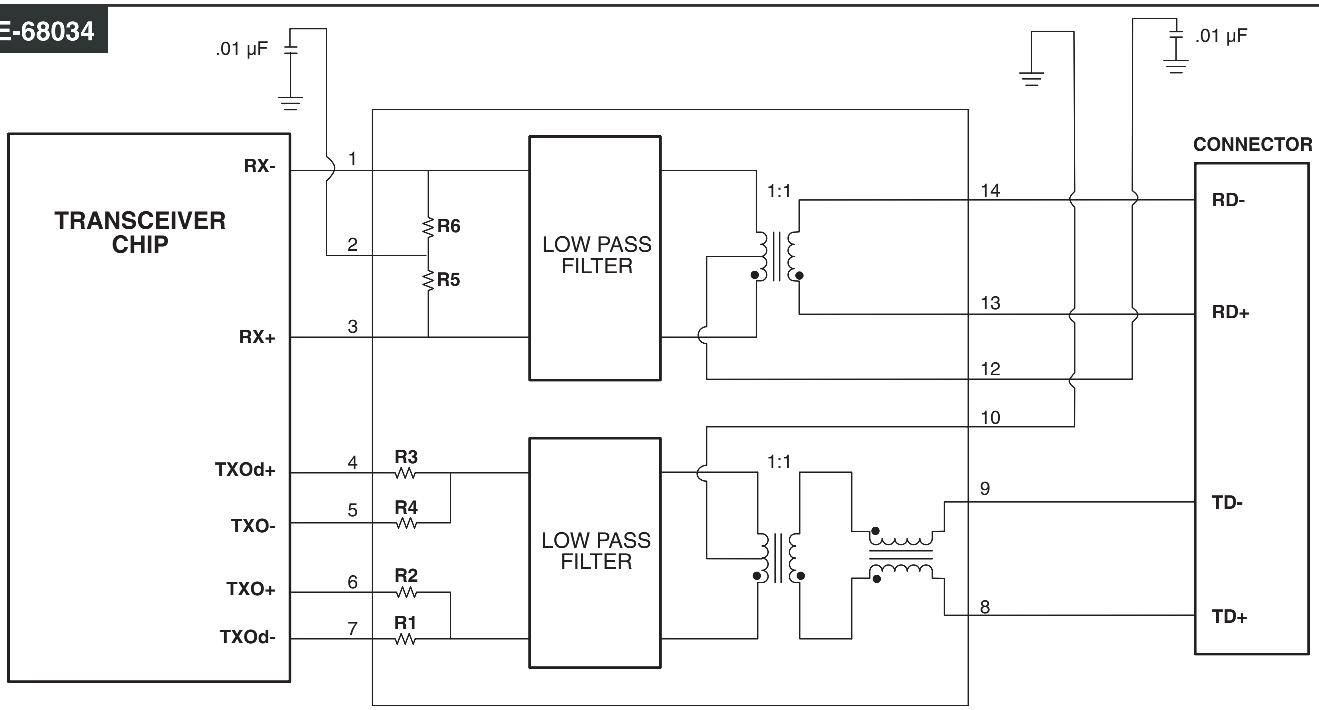


LOW PROFILE SURFACE MOUNT 10BASE-T INTERFACE MODULES

Ideal for Type I or Type II PCMCIA Applications

Application Circuit - C

PE-68034



Resistor Chart

Product Number	Resistor Number	Resistor Value	IC	IC Number	Application Circuit
PE-68032	NONE	N/A	Most	N/A	A
PE-68034	R1, R3	287 Ω ±1%	National	DP83902VJG DP83934	C
	R2, R4	68.1 Ω ±1%			
	R5, R6	49.9 Ω ±1%			
PE-68035	R1, R4	53.6 Ω ±1%	AMD	AM79C96A AM79C940	A
	R2, R3	316 Ω ±1%			
	R5, R6	49.9 Ω ±1%			
PE-68036	R1, R3	47.5 Ω ±1%	Motorola	MC68160	B
	R2, R4	N/A			
	R5, R6	49.9 Ω ±1%			

LOW PROFILE SURFACE MOUNT 10BASE-T INTERFACE MODULES

Ideal for Type I or Type II PCMCIA Applications

Application

Pulse's ThinSet™ 10Base-T modules are the optimum analog solution for PCMCIA applications. Primary design features include electrical functions, mechanical packaging and process standards.

Electrical Functions

• Impedance Matching • Equipment Isolation • EMI suppression

Each module contains low pass filters, isolation transformers, and common mode chokes. Most also include pre-emphasis and impedance matching resistors. Please refer to the appropriate application circuit and resistor chart for specific configurations.

Mechanical Packaging

• Dimensions • External Features • Internal Construction

The low .094" profile allows for use in both Type I and Type II applications. ThinSet™ modules are highly integrated to keep a compact form factor for improved thermal management. Compliant leads provide excellent solder-joint reliability with ±.002" coplanarity. Advanced mechanical design yields more consistent and repeatable electrical performance.

Process Standards

• SMT requirements • Quality Assurance • Construction Methods

Materials, resistant to high temperatures, have been selected for thermal compatibility to comply with industry standard reflow methods. Post dipping the leads helps ensure solderability to the PC board. Improved construction techniques increase package reliability in high stress environments.

Note:

Modules are packaged in tubes unless tape and reel is specified. Please add the suffix "T" (i.e. PE-68032**T**) for tape and reel orders, increments of 600 pieces.

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